

U.S. Department of Commerce, Patent and Trademark Office		Docket No.	Serial No.
		APPM/1931	08/856,116
LIST OF RELEVANT ART CITED BY APPLICANT		Applicant	
(REVERSE several sheets if necessary)		Liang-Yuh Chen, Fusen Chen, Moshe Eizenberg, and Roderick Craig Mosely	
		Filing Date	Group
		May 14, 1997	Unknown

## U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## Foreign Patent Documents

## Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

BES	AN	K. Mikagi, H. Ishikawa, T. Usami, M. Suzuki, K. Inoue, N. Oda, S. Chikaki, I. Sakai and T. Kikkawa, "Barrier Metal Free Copper Damascene Interconnection Technology Using Atmospheric Copper Reflow and Nitrogen Doping in SiOF Film." 1996 IEEE. pp. 365-368
BES	AO	Y. Shacham-Diamand, V. Dubin and M. Angyal, "Electroless Copper Deposition for ULSI," 1995 Elsevier Science S.A.. pp. 93-103
BES	AP	Electromigration and Diffusion in Pure Cu and Cu(Sn) Alloys. C.-K. Hu, K. L. Lee, D. Gupta, and P. Blauner, Mat. Res. Soc. Symp. Vol 427, (96-105)

Examiner Bernard E. Soun Date Considered 07/02/99

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

U.S. Department of Commerce, Patent and Trademark Office		Docket No.	Serial No.
<b>O I P E</b>		APPM/1931	08/856,116
LIST OF RELEVANT ART CITED BY APPLICANT <i>(use several sheets if necessary)</i>		Applicant	
		Liang-Yuh Chen, Fusen Chen, Moshe Eizenberg, and Roderick Craig Mosely	
		Filing Date	Group
		May 14, 1997	Unknown

## U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

## Foreign Patent Documents

## Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
	AL							
	AM							
	AN							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>BES</i>	AO	Electromigration Failure Distributions for Multi-Large Interconnects as a Function of Line Width: Experiments and Simulation. D.D. Brown, J.E. Sanchez, Jr., V. Pham, P.R. Besser, M.A. Korhonen, and C.-Y. Li, Mat. Res. Soc. Symp. Vol 427
	AP	
	AQ	

Examiner *Bernard E. Sow* Date Considered *07/02/99*

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.